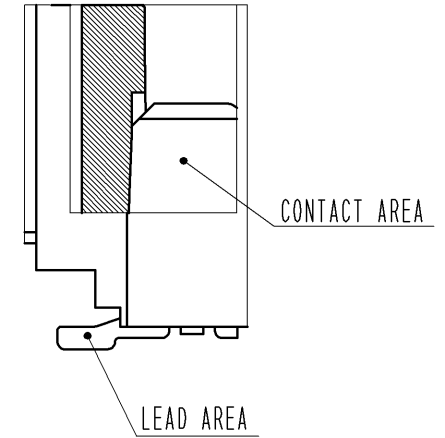


A (10:1)

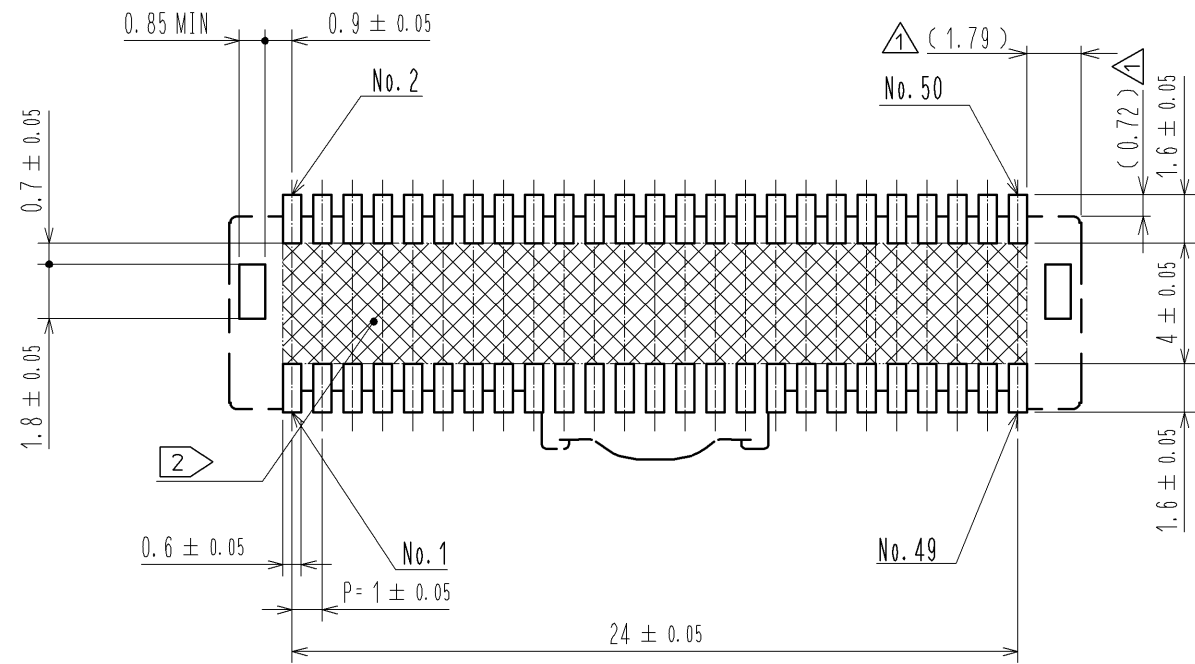


- NOTES
1. LEAD CO-PLANARITY SHALL BE 0.1 mm MAX.
 2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

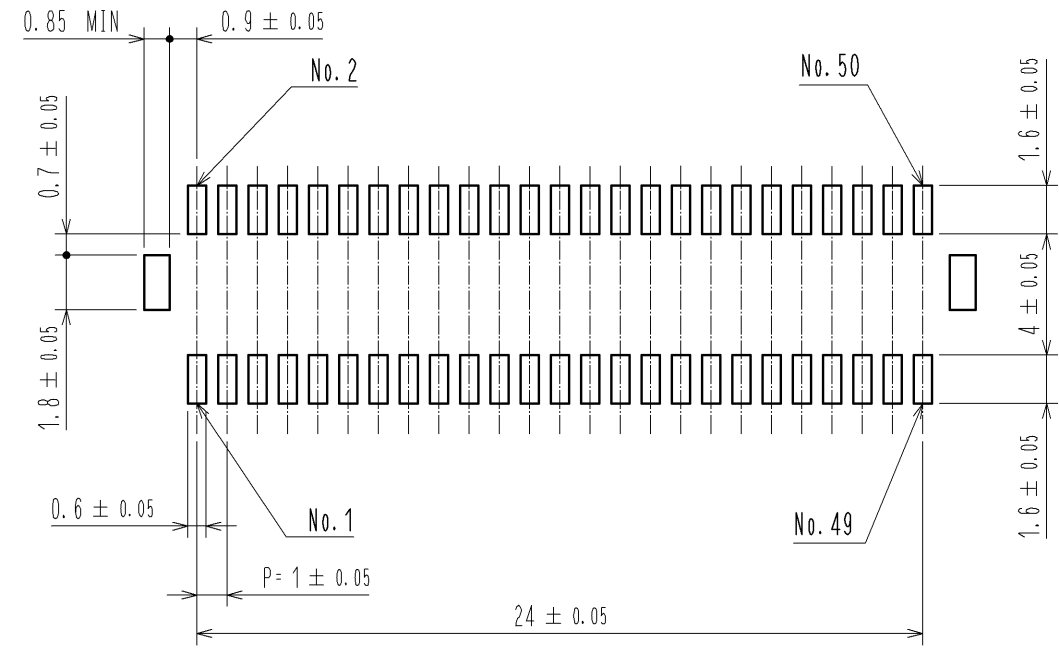
3	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN.	9	POLYAMIDE	VACUUM CAP
		LEAD AREA : Au PLATING 0.05μm MIN.	8	PS	REEL, BLACK
		UNDERPLATING : Ni PLATING 1μm MIN.	7	POLYESTER	CLEAR
2	BRASS	CONTACT AREA : Au PLATING 0.05μm MIN.	6	PS	CLEAR
		LEAD AREA : Au PLATING 0.05μm MIN.	5	STAINLESS STEEL	-
		UNDERPLATING : Ni PLATING 1μm MIN.	4	BRASS	SURFACE : Sn PLATING 1μm MIN. UNDERPLATING : Ni PLATING 0.5μm MIN.
1	LCP	BLACK, UL94V-0			
NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS

UNITS mm		SCALE FREE	COUNT 4	DESCRIPTION OF REVISIONS DIS-H-007735	DESIGNED MI. SAKIMURA	CHECKED TS. KUMAZAWA	DATE 13. 03. 22
APPROVED : KI. AKIYAMA 12. 05. 31				DRAWING NO. EDC3-330237-02			
CHECKED : HK. UMEHARA 12. 05. 31				PART NO. DF50-50DP-1V(52)			
DESIGNED : TT. OHSAKO 12. 05. 30				CODE NO. CL665-0011-1-52			
DRAWN : TT. OHSAKO 12. 05. 30				1/3			

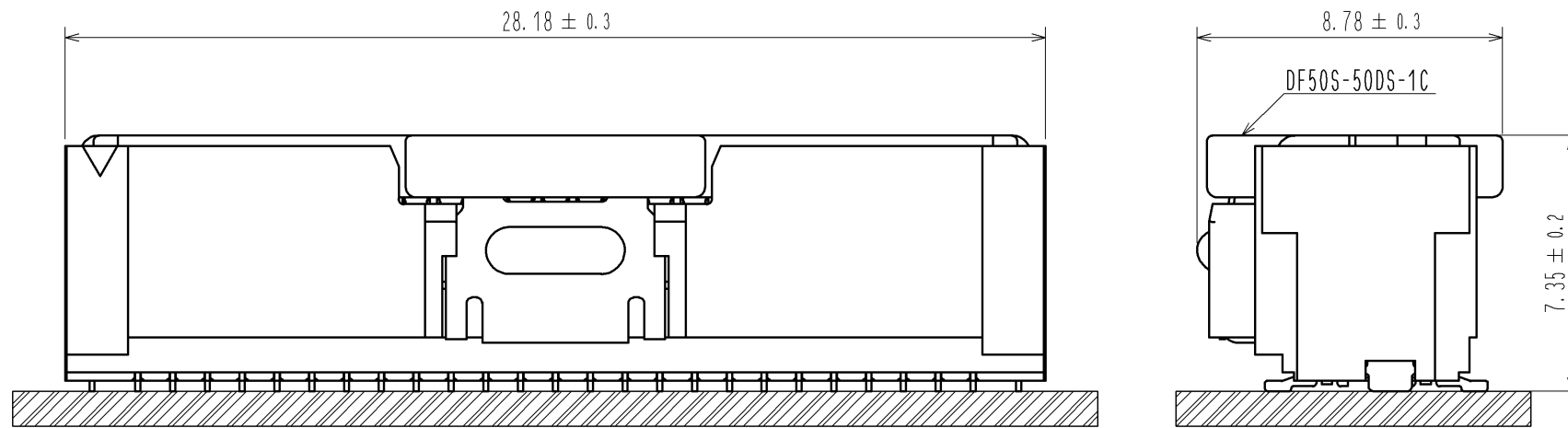
RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)



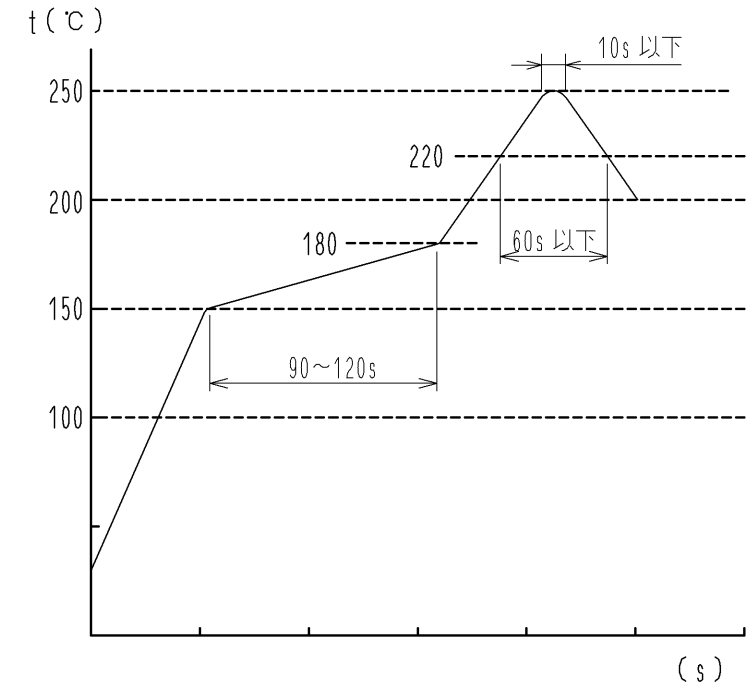
RECOMMENDED METAL MASK (FREE)
THICKNESS : 0.1mm



MATING FIGURE (5 : 1)



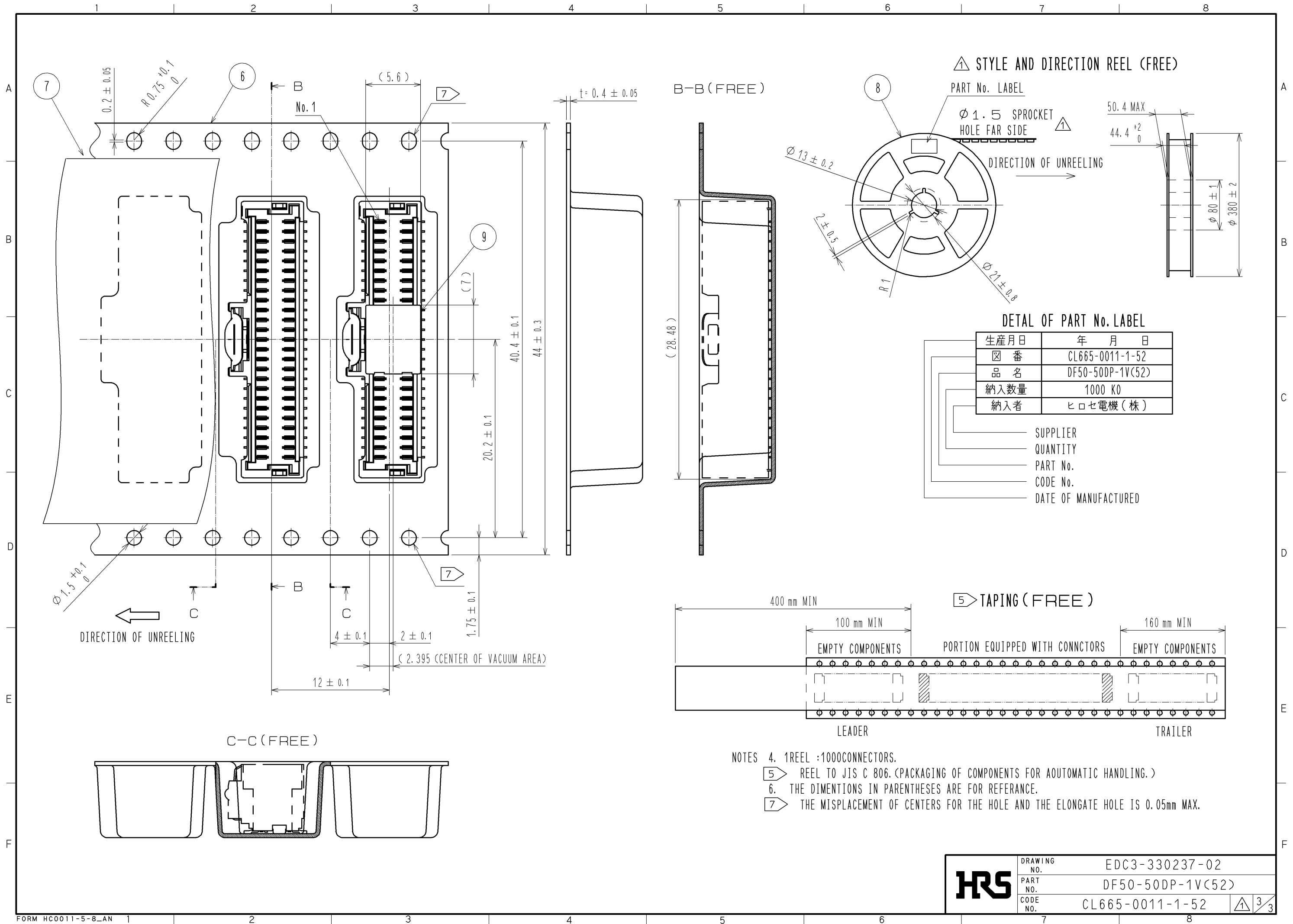
REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE(REFERENCE)



NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING
CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED
BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING
METAL etc.

HRS	DRAWING NO.	EDC3-330237-02
	PART NO.	DF50-50DP-1V(52)
	CODE NO.	CL665-0011-1-52
		\triangle 2/3



HRS	DRAWING NO.	EDC3-330237-02
	PART NO.	DF50-50DP-1V(52)
	CODE NO.	CL665-0011-1-52
		3/3